

Single-side (TOP) load for all components White LPI solder mask Black silkscreen IPC-4552 ENIG finish, no Pb

Ideal layer stackup (top to bottom):
1 oz/1.4mil top/layer 1 copper
6.7mil prepreg
0.5 oz/0.7mil layer 2 copper
47 mil core
0.5 oz/0.7mil layer 3 copper
6.7mil prepreg
1 oz/1.4mil bottom/layer 4 copper

All copper layers positive PCB thickness 62mil/1.6mm total FR4 or FR408 material

4 thru-hole connectors: USB1 (vertical RA USB-A connector) P1 (Right-angle 2x5 header) VBAT4/VBUS Out: Red banana jack GND4/GND: Black banana jack

Board cutout dimension marked "CUTOUT": 325 x 550mil